

Connector for microSD™ Card (Push-push Type)

SCHA Series



Compact low-profile type most suitable for mobile phones.

For
SD Memory
Card

For
microSD™
Card

For
SIM Card
8pins

For
W-SIM

For
Memory
Stick Micro™

For
Memory
Stick™

Combine Type

For
Compact
Flash™

For PC cards
supporting
CardBus

For
Express
Card™

For CMOS
Camera Module



Features

- Improved operability from a clear click feel.
- Good operational feel.

Applications

- For mobile phones, personal digital assistants, digital still cameras, compact audio equipment.

Typical Specifications

Items			Specifications
Structure	Applicable media		microSD™ Card
	Mounting type		Surface mounting type
	Mounting style		Standard mount/Reverse mount
	Media ejection structure		Push-push type
Performance	Operating temperature range		−20℃ to +70℃
	Voltage proof		500V AC 1minute
	Insulation resistance (Initial)		1,000MΩ min.
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
	Insertion and removal cycle		5,000cycles

Product Line

Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	Without switch	0	Taping	SCHA1A0101	1
		With switch			SCHA1B0100	2
	Reverse mount				SCHA2B0300	3

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1	Without switch	
2	With switch	

For CMOS
Camera Module

■ Dimensions
Reverse mount

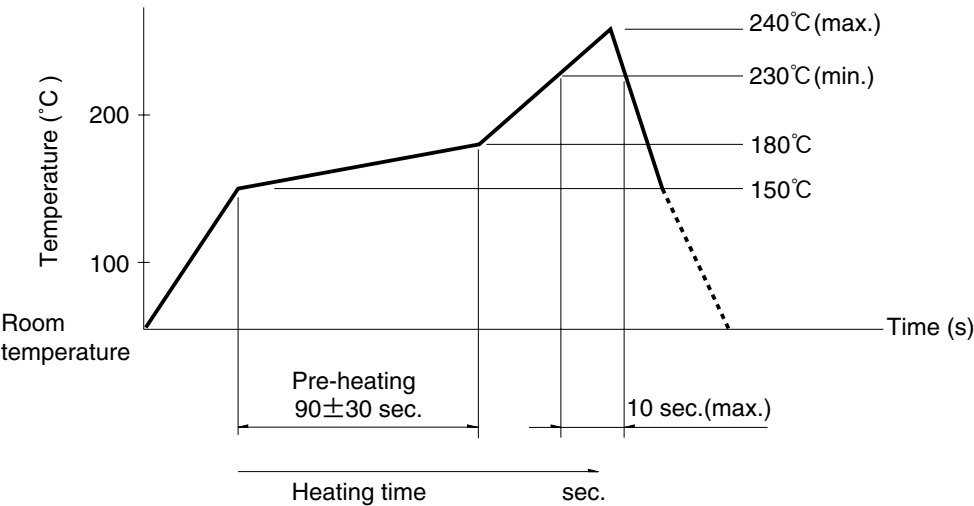
Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
3	With switch	Technical drawing showing the PC board mounting hole dimensions for Style 3 (With switch). The drawing includes a top view, a side view, and a front view. The top view shows a rectangular board with a central connector area and a card center. Dimensions include overall width (14), overall height (13), and various offsets (0.85, 0.95, 3.81, 0.4). Pin locations are marked: Pin1, Dummy, Pin2, Pin3, Pin4 on the left; Pin8, Dummy, Pin7, Pin6, Pin5 on the right. A 'Common' terminal and a 'Card detect switch' are also shown. The side view shows a height of 16.1 and a width of 1.9. The front view shows a width of 0.35. A legend indicates 'Land area' with a hatched box and 'No parts area' with a dashed box.

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) .
- 3. Temperature profile (Surface of products) .



Cautions for using this product

- 1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
- 2. Avoid use of water-soluble soldering flux, since it may corrode the product.
- 3. Check and conform to reflow soldering requirements under actual mass production conditions.
- 4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
- 5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.